



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-15
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8HZG*TWU022D	A	BOUSKOURA B/E	2015-06-15
Amount	UoM	Unit type	ST ECOPACK Grade	
98	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.2, 3.7, 2.37	2	J BEND	
Comment	Package: SMB CLIP (SOD 6), MD valid for CP:SM6T22A,SMBJ18A-TR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HZG*TWU022D					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	1.601	mg	supplier	die	Silicon (Si)	7440-21-3		1.572	mg	981898	16051
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	3121	51
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	3745	61
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.006	mg		
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1248	20
Leadframe	Copper & its alloys	41.514	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	6242	102
				supplier	alloy	Copper (Cu)	7440-50-8		40.623	mg	978537	414520
				supplier	alloy	Iron (Fe)	7439-89-6		0.041	mg	988	418
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	289	122
				supplier	metallization	Nickel (Ni)	7440-02-0		0.833	mg	20066	8500
Soft solder	Solder	1.568	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.466	mg	934949	14959
				supplier	solder	Tin (Sn)	7440-31-5		0.078	mg	49745	796
				supplier	solder	Silver (Ag)	7440-22-4		0.024	mg	15306	245
				supplier	metallization	Phosphorus (P)	12185-10-3		0.005	mg	120	51
				supplier	metallization	Lead (Pb)	7439-92-1		1.466	mg	934949	14959
Encapsulation	Other Organic Materials	34.176	mg	supplier	mold compound	Silica, vitreous	60676-86-0		25.973	mg	759978	265031
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		3.486	mg	102001	35571
				supplier	mold compound	Phenol resin	9003-35-4		2.051	mg	60013	20929
				supplier	mold compound	Others	Proprietary		1.709	mg	50006	17439
				supplier	mold compound	Metal hydroxide	Proprietary		0.684	mg	20014	6980
connections coating	Solder	0.811	mg	supplier	mold compound	Carbon black	1333-86-4		0.273	mg	7988	2786
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.811	mg	1000000	8276
Clip	Clip	18.330	mg	supplier	alloy	Copper (Cu)	7440-50-8		18.330	mg	1000000	187041